

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Glen B. Cook  
Patrick Gedeon  
Jeffrey M. King  
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Examiner: To Be Assigned

Serial No: To Be Assigned

Group Art Unit: To Be Assigned

Filed: Herewith

For: DIRECT BONDING OF GLASS  
ARTICLES FOR DRAWING

jc997 U.S. PTO  
10/035659  
10/26/01

#2

**INFORMATION DISCLOSURE STATEMENT  
UNDER 37 C.F.R. §§ 1.56, 1.97 – 1.98**

Asst. Commissioner of Patents and Trademarks  
Washington, DC 20231

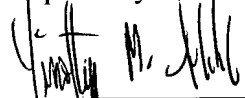
Dear Sir:

The Examiner's attention is hereby directed to the following reference(s) listed on the attached Form PTO-1449 for consideration in connection with the examination of the above-identified patent application. One copy of the reference(s) is enclosed.

This submission does not represent that a search has been made or that no better art exists and does not constitute an admission that each or all of the enclosed documents constitute "prior art." If it should be determined that any of the submitted documents do not constitute "prior art" under United States law, applicant(s) reserve the right to present to the office the relevant facts and law regarding the appropriate status of such documents.

Applicant(s) further reserve the right to take appropriate action to establish the patentability of the disclosed invention over the enclosed references, should one or more of the references be applied against the claims of the present application.

Respectfully submitted,

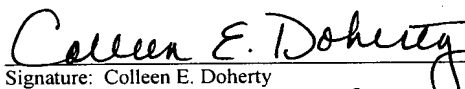
  
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I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to Asst. Commissioner of Patents and Trademarks, Washington, D.C. 20231 on

10-26-01

(Date)

  
Signature: Colleen E. Doherty

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FORM PTO-1449 (MODIFIED)  LIST OF PATENTS AND PUBLICATIONS  FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT	ATTORNEY DOCKET NO. SP01-302	SERIAL NO. To Be Assigned
	APPLICANT Cook et al.	
	FILING DATE: Herewith	GROUP: To Be Assigned

Jc997 U.S. PTO  
 10/035659



REFERENCE DESIGNATION				U.S. PATENT DOCUMENTS			
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA	5,915,193	6/22/99	Tong et al.	438	455	
	AB	5,785,874	7/28/98	Eda	216	24	
	AC	5,932,048	8/3/99	Furukawa et al.	156	153	
	AD	6,129,854	10/10/00	Ramsey et al.	216	18	
	AE	6,153,495	11/28/00	Kub et al.	438	459	
	AF	6,178,779	1/30/01	Drouart et al.	65	391	
	AG	6,098,429	8/8/01	Mazabraud et al.	65	392	
	AH	4,407,667	10/4/83	LeNoane et al.	65	3.11	

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
	AI	1 057 793A1	12/6/00	EPO	C03B	37/027	X

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)		
AJ	A. Sayah, D. Solignac, T. Cueni, "Development of novel low temperature bonding technologies for microchip chemical analysis applications," Sensors and Actuators, 84 (2000) pp. 103-108.	
AK	P. Rangsten, O. Vallin, K. Hermansson, Y. Backlund, "Quartz-to-Quartz Direct bonding," J. Electrochemical Society, V. 146, N. 3, pp. 1104-1105, 1999).	
AL	H. Nakanishi, T. Nishimoto, M. Kani, T. Saitoh, R. Nakamura, T. Yoshida, S. Shoji, "Condition Optimization, Reliability Evaluation of SiO <sub>2</sub> -SiO <sub>2</sub> HF Bonding and Its Application for UV Detection Micro Flow Cell," Sensors and Actuators, V. 83, pp. 136-141, 2000.	
AM	A. Yamada, et al., Bonding Silicon wafer to Silicon Nitride With Spin-on Glass Adhesive, Electronics Letters, March 26, 1987, Vol. 23, No. 7.	
AN	D.J. Harrison, et al., Micromachining a Miniaturized Capillary Electrophoresis-Based Chemical Analysis System on a Chip, Science 261 (1993) 895-897.	
AO	W.P. Maszara, Silicon-on-insulator by Wafer Bonding: A Review, J. Electrochemical Society 138 (1991) 341-347.	
AP	D-W. Shin, et al., The Stacking Faults and Their Strain Effect at the Si/SiO <sub>2</sub> Interfaces of a Directly Bonded SOI (silicon on insulator), Thin Solid Films, V. 346, pp. 169-173, 1999.	
AQ	Q-Y. Tong, et al., The Role of Surface Chemistry in Bonding of Standard Silicon Wafers, J. Electrochemical Society V. 144, N. 1, pp. 384-389, 1997	

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.